

METHOD FOR MINIMIZING SLIP LINE FAULTS ON A SEMICONDUCTOR WAFER SURFACE

ABSTRACT

5 A method for minimizing slip line faults on a surface of a semiconductor
wafer that has been obtained using a transfer technique. The method includes
heating the semiconductor wafer from an ambient temperature to a first higher
temperature and pausing the heating at the first higher temperature for a time
sufficient to stabilize the wafer. Then the wafer is heated further from the first
higher temperature to a target higher temperature during a predetermined time
10 interval. The further heating during an initial portion of the time interval is
conducted at a relatively low heating rate and the heating during a final portion of the
time interval is conducted at a relatively higher heating rate to thus minimize slip line
faults in the surface of the wafer.

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